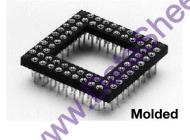
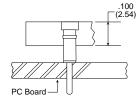


# Low Insertion Force PGA Sockets

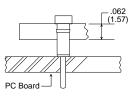
5 Energy Way, P.O. Box 1019, West Warwick, RI 02893 USA Tel. 800-424-9850/401-823-5200 • Fax 401-823-8723 • Email info@advintcorp.com • Internet http://www.advintcorp.com

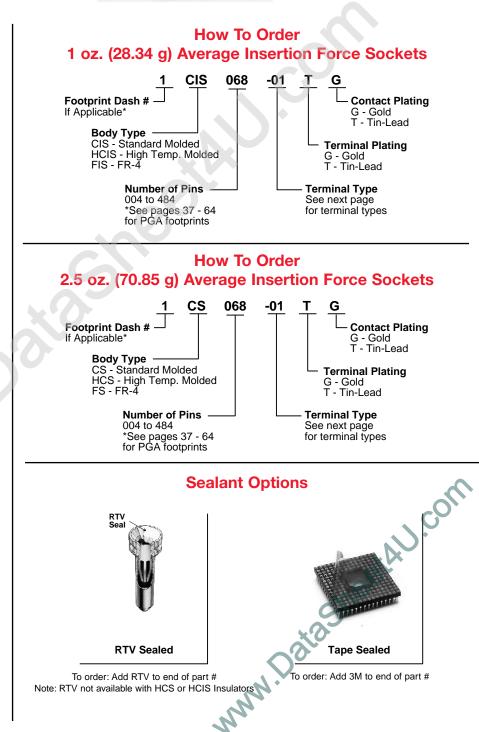
# Molded & FR-4 Low Insertion Force PGA Sockets











### **Features**

- As low as 1 oz.(28.34 g) average insertion force per pin.
- Multiple finger contacts for reliability.
- Over 500 PGA footprints available.
- Closed bottom terminal for 100% antiwicking of solder.
- Tapered entry for ease of insertion.
- To fit .100" (2.54 mm) grid.
- Easily customized to fit your application.

#### **Terminals and Contacts:**

Terminal: Brass - Copper Alloy (C36000) ASTM-B-16 Contact: Beryllium Copper (C17200) ASTM-B-194

#### Solder Preform:

63% Tin, 37% Lead

#### **Plating:**

Terminal: Gold over Nickel or Tin-Lead over Nickel Contact: Gold over Nickel or Tin-Lead over Nickel Gold per MIL-G-45204 Tin-Lead per MIL-P-81728 Nickel per QQ-N-290

#### **Body Material:**

**CS/CIS** - Glass Filled Thermoplastic Polyester (P.B.T.), U.L. Rated 94V-O, -60°C to 140°C (-76°F to 284°F)

**HCS/HCIS** - High Temp. Glass Filled Thermoplastic (P.P.S.) , U.L. Rated 94V-O, -60°C to 260°C (-76°F to 500°F)

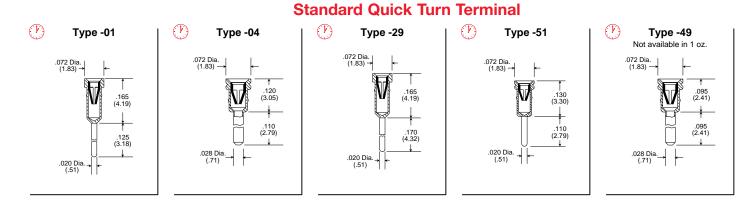
**FS/FIS -** FR-4 Fiberglass Epoxy Board, U.L. Rated 94V-O, Index 140°C (284°F)



# Low Insertion Force PGA Sockets

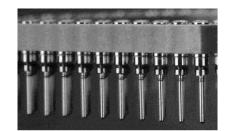
5 Energy Way, P.O. Box 1019, West Warwick, RI 02893 USA Tel. 800-424-9850/401-823-5200 • Fax 401-823-8723 • Email info@advintcorp.com • Internet http://www.advintcorp.com

## **Terminals for Molded & FR-4 Low Insertion Force PGA Sockets**



 $\ref{linear}$  Quick turn delivery available on standard terminal types. Additional terminal types available. See terminal section for detailed terminal information.

## Solder Preform PGA Sockets - Intrusive Reflow Application



#### Features:

- Combines the labor of socket loading and solder application into one operation.
- Eliminates the use of solder paste and screening operation.
- Eliminates solder bridges and/or solder shorts due to excess solder.
- Ensures a reliable solder joint with controlled solder volume.
- Ideal for surface mount and mixed technology applications.
- For custom solder preform terminal applications consult factory.
- See previous page for material specifications and how to order information.

